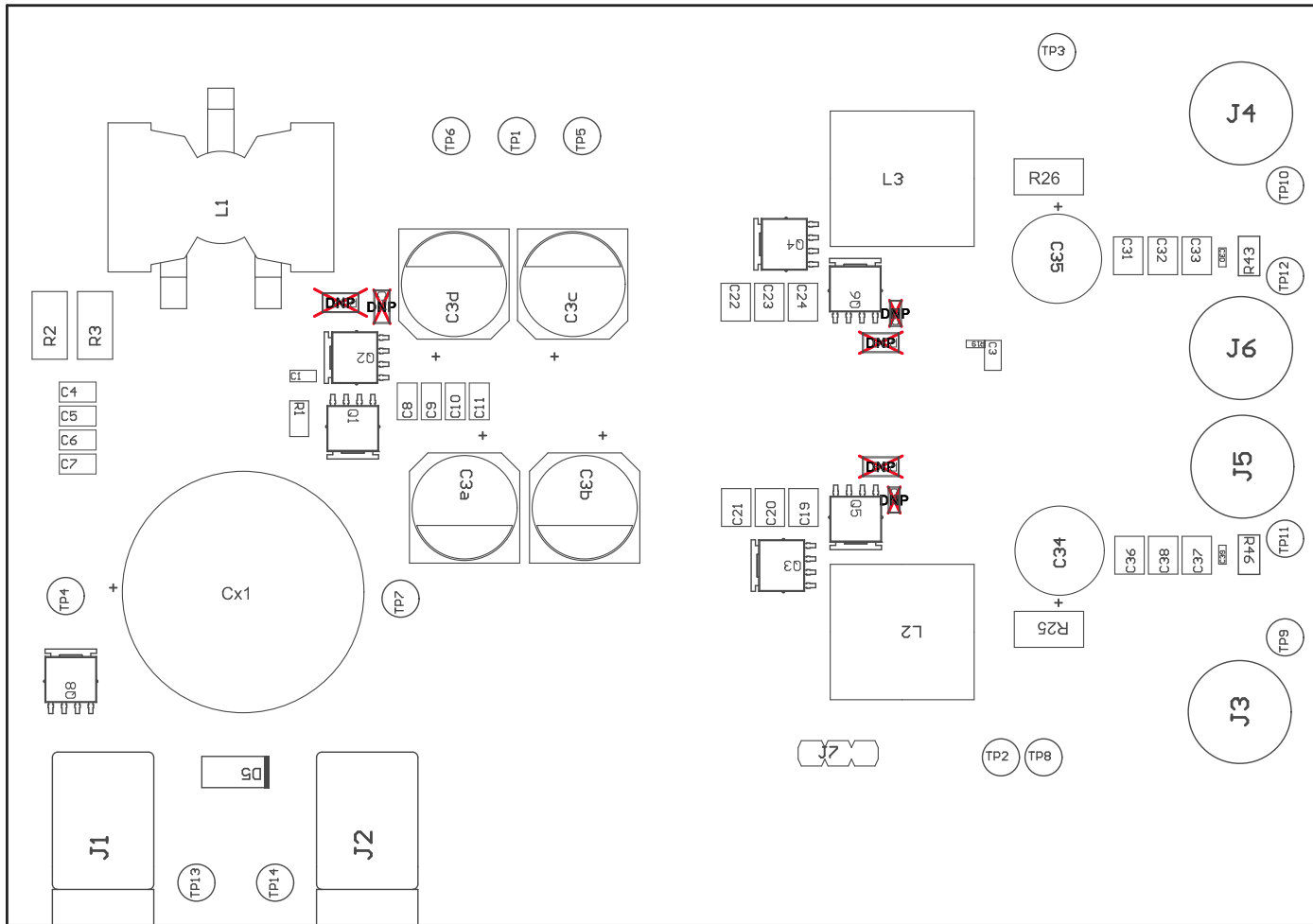


zz2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

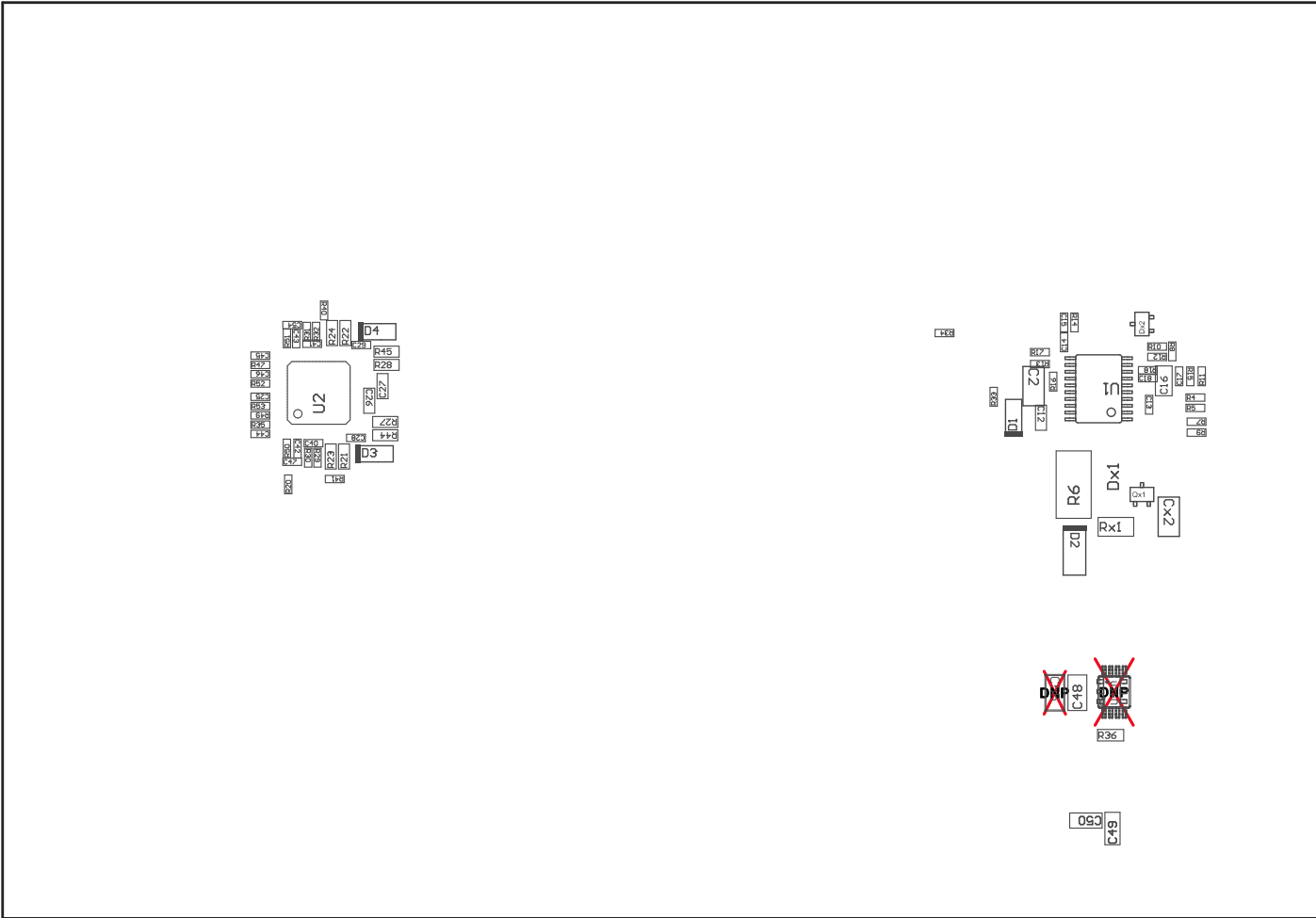
zz3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

zz4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
	TID #: TIDA-01553		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/19/2017 7:13:37 AM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
	TID #: TIDA-01553		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/19/2017 7:13:39 AM		TEXAS INSTRUMENTS

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